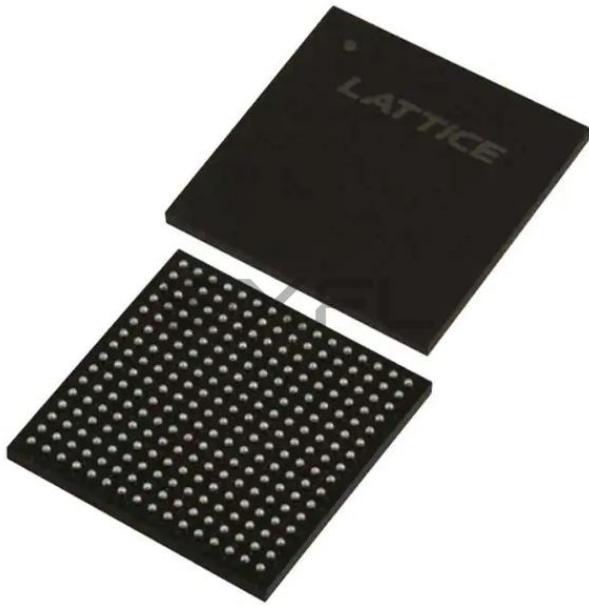




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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Active
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	-
Number of I/O	128
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	256-LBGA
Supplier Device Package	256-FTBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4256v-5ftn256ac

Table 2. ispMACH 4000Z Family Selection Guide

	ispMACH 4032ZC	ispMACH 4064ZC	ispMACH 4128ZC	ispMACH 4256ZC
Macrocells	32	64	128	256
I/O + Dedicated Inputs	32+4/32+4	32+4/32+12/ 64+10/64+10	64+10/96+4	64+10/96+6/ 128+4
t _{PD} (ns)	3.5	3.7	4.2	4.5
t _S (ns)	2.2	2.5	2.7	2.9
t _{CO} (ns)	3.0	3.2	3.5	3.8
f _{MAX} (MHz)	267	250	220	200
Supply Voltage (V)	1.8	1.8	1.8	1.8
Max. Standby I _{CC} (μA)	20	25	35	55
Pins/Package	48 TQFP 56 csBGA	48 TQFP 56 csBGA 100 TQFP 132 csBGA	100 TQFP 132csBGA	100 TQFP 132 csBGA 176 TQFP

ispMACH 4000 Introduction

The high performance ispMACH 4000 family from Lattice offers a SuperFAST CPLD solution. The family is a blend of Lattice's two most popular architectures: the ispLSI® 2000 and ispMACH 4A. Retaining the best of both families, the ispMACH 4000 architecture focuses on significant innovations to combine the highest performance with low power in a flexible CPLD family.

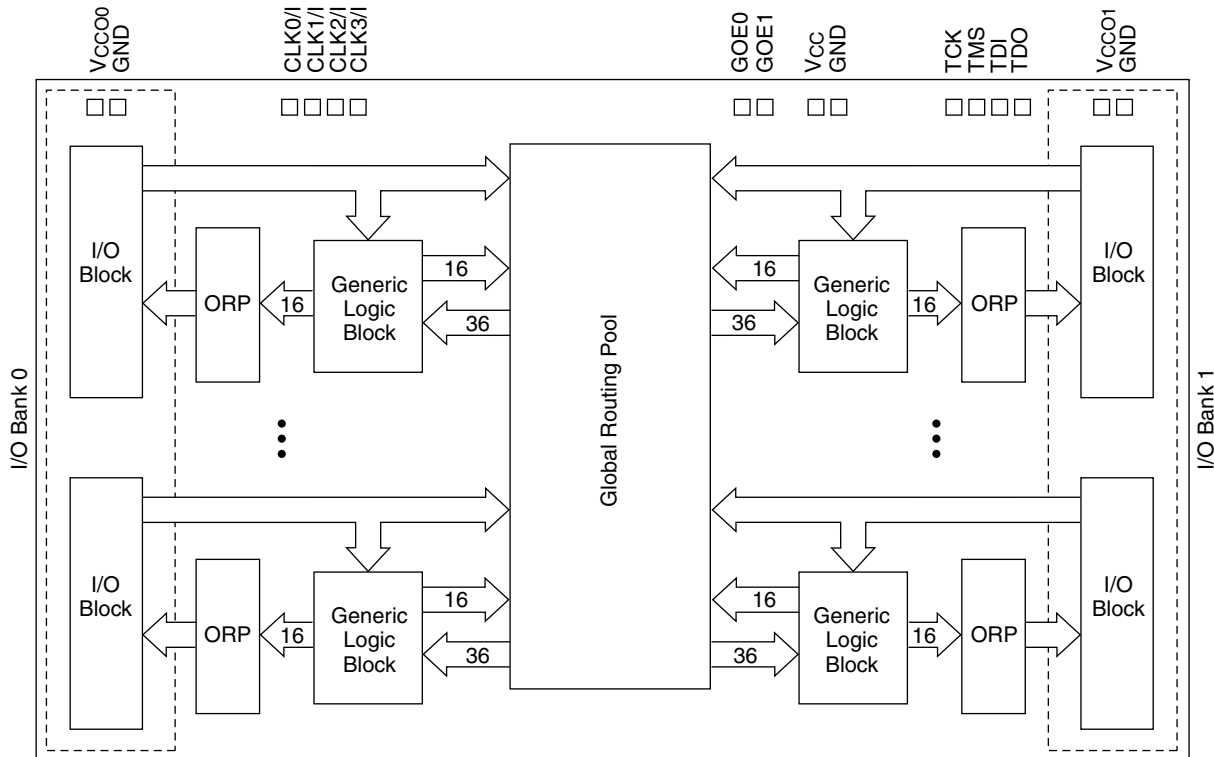
The ispMACH 4000 combines high speed and low power with the flexibility needed for ease of design. With its robust Global Routing Pool and Output Routing Pool, this family delivers excellent First-Time-Fit, timing predictability, routing, pin-out retention and density migration.

The ispMACH 4000 family offers densities ranging from 32 to 512 macrocells. There are multiple density-I/O combinations in Thin Quad Flat Pack (TQFP), Chip Scale BGA (csBGA) and Fine Pitch Thin BGA (ftBGA) packages ranging from 44 to 256 pins/balls. Table 1 shows the macrocell, package and I/O options, along with other key parameters.

The ispMACH 4000 family has enhanced system integration capabilities. It supports 3.3V (4000V), 2.5V (4000B) and 1.8V (4000C/Z) supply voltages and 3.3V, 2.5V and 1.8V interface voltages. Additionally, inputs can be safely driven up to 5.5V when an I/O bank is configured for 3.3V operation, making this family 5V tolerant. The ispMACH 4000 also offers enhanced I/O features such as slew rate control, PCI compatibility, bus-keeper latches, pull-up resistors, pull-down resistors, open drain outputs and hot socketing. The ispMACH 4000 family members are 3.3V/2.5V/1.8V in-system programmable through the IEEE Standard 1532 interface. IEEE Standard 1149.1 boundary scan testing capability also allows product testing on automated test equipment. The 1532 interface signals TCK, TMS, TDI and TDO are referenced to V_{CC} (logic core).

Overview

The ispMACH 4000 devices consist of multiple 36-input, 16-macrocell Generic Logic Blocks (GLBs) interconnected by a Global Routing Pool (GRP). Output Routing Pools (ORPs) connect the GLBs to the I/O Blocks (IOBs), which contain multiple I/O cells. This architecture is shown in Figure 1.

Figure 1. Functional Block Diagram

The I/Os in the ispMACH 4000 are split into two banks. Each bank has a separate I/O power supply. Inputs can support a variety of standards independent of the chip or bank power supply. Outputs support the standards compatible with the power supply provided to the bank. Support for a variety of standards helps designers implement designs in mixed voltage environments. In addition, 5V tolerant inputs are specified within an I/O bank that is connected to V_{CC0} of 3.0V to 3.6V for LVCMOS 3.3, LVTTTL and PCI interfaces.

ispMACH 4000 Architecture

There are a total of two GLBs in the ispMACH 4032, increasing to 32 GLBs in the ispMACH 4512. Each GLB has 36 inputs. All GLB inputs come from the GRP and all outputs from the GLB are brought back into the GRP to be connected to the inputs of any other GLB on the device. Even if feedback signals return to the same GLB, they still must go through the GRP. This mechanism ensures that GLBs communicate with each other with consistent and predictable delays. The outputs from the GLB are also sent to the ORP. The ORP then sends them to the associated I/O cells in the I/O block.

Generic Logic Block

The ispMACH 4000 GLB consists of a programmable AND array, logic allocator, 16 macrocells and a GLB clock generator. Macrocells are decoupled from the product terms through the logic allocator and the I/O pins are decoupled from macrocells through the ORP. Figure 2 illustrates the GLB.

Table 7. ORP Combinations for I/O Blocks with 16 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M1, M2, M3, M4, M5, M6, M7, M8
I/O 2	M2, M3, M4, M5, M6, M7, M8, M9
I/O 3	M3, M4, M5, M6, M7, M8, M9, M10
I/O 4	M4, M5, M6, M7, M8, M9, M10, M11
I/O 5	M5, M6, M7, M8, M9, M10, M11, M12
I/O 6	M6, M7, M8, M9, M10, M11, M12, M13
I/O 7	M7, M8, M9, M10, M11, M12, M13, M14
I/O 8	M8, M9, M10, M11, M12, M13, M14, M15
I/O 9	M9, M10, M11, M12, M13, M14, M15, M0
I/O 10	M10, M11, M12, M13, M14, M15, M0, M1
I/O 11	M11, M12, M13, M14, M15, M0, M1, M2
I/O 12	M12, M13, M14, M15, M0, M1, M2, M3
I/O 13	M13, M14, M15, M0, M1, M2, M3, M4
I/O 14	M14, M15, M0, M1, M2, M3, M4, M5
I/O 15	M15, M0, M1, M2, M3, M4, M5, M6

Table 8. ORP Combinations for I/O Blocks with 4 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M4, M5, M6, M7, M8, M9, M10, M11
I/O 2	M8, M9, M10, M11, M12, M13, M14, M15
I/O 3	M12, M13, M14, M15, M0, M1, M2, M3

Table 9. ORP Combinations for I/O Blocks with 10 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M2, M3, M4, M5, M6, M7, M8, M9
I/O 2	M4, M5, M6, M7, M8, M9, M10, M11
I/O 3	M6, M7, M8, M9, M10, M11, M12, M13
I/O 4	M8, M9, M10, M11, M12, M13, M14, M15
I/O 5	M10, M11, M12, M13, M14, M15, M0, M1
I/O 6	M12, M13, M14, M15, M0, M1, M2, M3
I/O 7	M14, M15, M0, M1, M2, M3, M4, M5
I/O 8	M2, M3, M4, M5, M6, M7, M8, M9
I/O 9	M10, M11, M12, M13, M14, M15, M0, M1

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M1, M2, M3, M4, M5, M6, M7, M8
I/O 2	M2, M3, M4, M5, M6, M7, M8, M9
I/O 3	M4, M5, M6, M7, M8, M9, M10, M11
I/O 4	M5, M6, M7, M8, M9, M10, M11, M12
I/O 5	M6, M7, M8, M9, M10, M11, M12, M13
I/O 6	M8, M9, M10, M11, M12, M13, M14, M15
I/O 7	M9, M10, M11, M12, M13, M14, M15, M0
I/O 8	M10, M11, M12, M13, M14, M15, M0, M1
I/O 9	M12, M13, M14, M15, M0, M1, M2, M3
I/O 10	M13, M14, M15, M0, M1, M2, M3, M4
I/O 11	M14, M15, M0, M1, M2, M3, M4, M5

The ORP bypass and fast-path output multiplexer is a 4:1 multiplexer and allows the 5-PT fast path to bypass the ORP and be connected directly to the pin with either the regular output or the inverted output. This multiplexer also allows the register output to bypass the ORP to achieve faster t_{CO} .

The OE Routing Pool provides the corresponding local output enable (OE) product term to the I/O cell.

The I/O cell contains the following programmable elements: output buffer, input buffer, OE multiplexer and bus maintenance circuitry. Figure 8 details the I/O cell.

[illegible]

Each output supports a variety of output standards dependent on the V_{CCO} supplied to its I/O bank. Outputs can also be configured for open drain operation. Each input can be programmed to support a variety of standards, independent of the V_{CCO} supplied to its I/O bank. The I/O standards supported are:

I/O Recommended Operating Conditions

Standard	V_{CCO} (V) ¹	
	Min.	Max.
LVTTL	3.0	3.6
LVC MOS 3.3	3.0	3.6
Extended LVC MOS 3.3 ²	2.7	3.6
LVC MOS 2.5	2.3	2.7
LVC MOS 1.8	1.65	1.95
PCI 3.3	3.0	3.6

1. Typical values for V_{CCO} are the average of the min. and max. values.

2. ispMACH 4000Z only.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{IL}, I_{IH}^{1,4}$	Input Leakage Current (ispMACH 4000Z)	$0 \leq V_{IN} < V_{CCO}$	—	0.5	1	μA
I_{IH}^1	Input High Leakage Current (ispMACH 4000Z)	$V_{CCO} < V_{IN} \leq 5.5V$	—	—	10	μA
I_{IL}, I_{IH}^1	Input Leakage Current (ispMACH 4000V/B/C)	$0 \leq V_{IN} \leq 3.6V, T_j = 105^\circ C$	—	—	10	μA
		$0 \leq V_{IN} \leq 3.6V, T_j = 130^\circ C$	—	—	15	μA
$I_{IH}^{1,2}$	Input High Leakage Current (ispMACH 4000V/B/C)	$3.6V < V_{IN} \leq 5.5V, T_j = 105^\circ C$ $3.0V \leq V_{CCO} \leq 3.6V$	—	—	20	μA
		$3.6V < V_{IN} \leq 5.5V, T_j = 130^\circ C$ $3.0V \leq V_{CCO} \leq 3.6V$	—	—	50	μA
I_{PU}	I/O Weak Pull-up Resistor Current (ispMACH 4000Z)	$0 \leq V_{IN} \leq 0.7V_{CCO}$	-30	—	-150	μA
	I/O Weak Pull-up Resistor Current (ispMACH 4000V/B/C)	$0 \leq V_{IN} \leq 0.7V_{CCO}$	-30	—	-200	μA
I_{PD}	I/O Weak Pull-down Resistor Current	$V_{IL} (MAX) \leq V_{IN} \leq V_{IH} (MIN)$	30	—	150	μA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL} (MAX)$	30	—	—	μA
I_{BHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7 V_{CCO}$	-30	—	—	μA
I_{BHLO}	Bus Hold Low Overdrive Current	$0V \leq V_{IN} \leq V_{BHT}$	—	—	150	μA
I_{BHHO}	Bus Hold High Overdrive Current	$V_{BHT} \leq V_{IN} \leq V_{CCO}$	—	—	-150	μA
V_{BHT}	Bus Hold Trip Points	—	$V_{CCO} * 0.35$	—	$V_{CCO} * 0.65$	V
C_1	I/O Capacitance ³	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	8	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—		—	
C_2	Clock Capacitance ³	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	6	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—		—	
C_3	Global Input Capacitance ³	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	6	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—		—	

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tristated. It is not measured with the output driver active. Bus maintenance circuits are disabled.

2. 5V tolerant inputs and I/O should only be placed in banks where $3.0V \leq V_{CCO} \leq 3.6V$.

3. $T_A = 25^\circ C$, $f = 1.0MHz$

4. I_{IH} excursions of up to 1.5 μA maximum per pin above the spec limit may be observed for certain voltage conditions on no more than 10% of the device's I/O pins.

ispMACH 4000Z External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description ^{1, 2, 3}	-35		-37		-42		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{PD}	5-PT bypass combinatorial propagation delay	—	3.5	—	3.7	—	4.2	ns
t _{PD_MC}	20-PT combinatorial propagation delay through macrocell	—	4.4	—	4.7	—	5.7	ns
t _S	GLB register setup time before clock	2.2	—	2.5	—	2.7	—	ns
t _{ST}	GLB register setup time before clock with T-type register	2.4	—	2.7	—	2.9	—	ns
t _{SIR}	GLB register setup time before clock, input register path	1.0	—	1.1	—	1.3	—	ns
t _{SIRZ}	GLB register setup time before clock with zero hold	2.0	—	2.1	—	2.6	—	ns
t _H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t _{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t _{HIR}	GLB register hold time after clock, input register path	1.0	—	1.0	—	1.3	—	ns
t _{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t _{CO}	GLB register clock-to-output delay	—	3.0	—	3.2	—	3.5	ns
t _R	External reset pin to output delay	—	5.0	—	6.0	—	7.3	ns
t _{RW}	External reset pulse duration	1.5	—	1.7	—	2.0	—	ns
t _{PTOE/DIS}	Input to output local product term output enable/disable	—	7.0	—	8.0	—	8.0	ns
t _{GPTOE/DIS}	Input to output global product term output enable/disable	—	6.5	—	7.0	—	8.0	ns
t _{GOE/DIS}	Global OE input to output enable/disable	—	4.5	—	4.5	—	4.8	ns
t _{CW}	Global clock width, high or low	1.0	—	1.5	—	1.8	—	ns
t _{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.0	—	1.5	—	1.8	—	ns
t _{WIR}	Input register clock width, high or low	1.0	—	1.5	—	1.8	—	ns
f _{MAX} ⁴	Clock frequency with internal feedback	—	267	—	250	—	220	MHz
f _{MAX} (Ext.)	clock frequency with external feedback, [1 / (t _S + t _{CO})]	—	192	—	175	—	161	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.2.2

2. Measured using standard switching GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

ispMACH 4000V/B/C Internal Timing Parameters (Cont.)**Over Recommended Operating Conditions**

Parameter	Description	-2.5		-2.7		-3		-3.5		Units
t_{PDLi}	Propagation Delay through Transparent Latch to Output/ Feedback MUX	—	0.25	—	0.25	—	0.25	—	0.25	ns
t_{SRi}	Asynchronous Reset or Set to Output/Feedback MUX Delay	0.28	—	0.28	—	0.28	—	0.28	—	ns
t_{SRR}	Asynchronous Reset or Set Recovery Time	1.67	—	1.67	—	1.67	—	1.67	—	ns
Control Delays										
t_{BCLK}	GLB PT Clock Delay	—	1.12	—	1.12	—	1.12	—	1.12	ns
t_{PTCLK}	Macrocell PT Clock Delay	—	0.87	—	0.87	—	0.87	—	0.87	ns
t_{BSR}	Block PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	—	1.83	ns
t_{PTSR}	Macrocell PT Set/Reset Delay	—	1.11	—	1.41	—	1.51	—	1.61	ns
t_{GPTOE}	Global PT OE Delay	—	2.83	—	4.13	—	5.33	—	5.33	ns
t_{PTOE}	Macrocell PT OE Delay	—	1.83	—	2.13	—	2.33	—	2.83	ns

Timing v.3.2

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the Timing Model in this data sheet for further details.

ispMACH 4000V/B/C Timing Adders¹

Adder Type	Base Parameter	Description	-25		-27		-3		-35		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Optional Delay Adders											
t _{INDIO}	t _{INREG}	Input register delay	—	0.95	—	1.00	—	1.00	—	1.00	ns
t _{EXP}	t _{MCELL}	Product term expander delay	—	0.33	—	0.33	—	0.33	—	0.33	ns
t _{ORP}	—	Output routing pool delay	—	0.05	—	0.05	—	0.05	—	0.05	ns
t _{BLA}	t _{ROUTE}	Additional block loading adder	—	0.03	—	0.05	—	0.05	—	0.05	ns
t _{IOI} Input Adjusters											
LVTTL_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVTTL standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVC MOS33_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 3.3 standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVC MOS25_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 2.5 standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVC MOS18_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 1.8 standard	—	0.00	—	0.00	—	0.00	—	0.00	ns
PCI_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using PCI compatible input	—	0.60	—	0.60	—	0.60	—	0.60	ns
t _{IOO} Output Adjusters											
LVTTL_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
LVC MOS33_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
LVC MOS25_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	—	0.10	ns
LVC MOS18_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	—	0.00	ns
PCI_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t _{BUF} , t _{EN}	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVC MOS timing.

Timing v.3.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding use of these adders.

Signal Descriptions

Signal Names	Description
TMS	Input – This pin is the IEEE 1149.1 Test Mode Select input, which is used to control the state machine.
TCK	Input – This pin is the IEEE 1149.1 Test Clock input pin, used to clock through the state machine.
TDI	Input – This pin is the IEEE 1149.1 Test Data In pin, used to load data.
TDO	Output – This pin is the IEEE 1149.1 Test Data Out pin used to shift data out.
GOE0/IO, GOE1/IO	These pins are configured to be either Global Output Enable Input or as general I/O pins.
GND	Ground
NC	Not Connected
V _{CC}	The power supply pins for logic core and JTAG port.
CLK0/I, CLK1/I, CLK2/I, CLK3/I	These pins are configured to be either CLK input or as an input.
V _{CC00} , V _{CC01}	The power supply pins for each I/O bank.
yzz	Input/Output ¹ – These are the general purpose I/O used by the logic array. y is GLB reference (alpha) and z is macrocell reference (numeric). z: 0-15.
	ispMACH 4032 y: A-B
	ispMACH 4064 y: A-D
	ispMACH 4128 y: A-H
	ispMACH 4256 y: A-P
	ispMACH 4384 y: A-P, AX-HX
	ispMACH 4512 y: A-P, AX-PX

1. In some packages, certain I/Os are only available for use as inputs. See the signal connections table for details.

ispMACH 4000V/B/C ORP Reference Table

	4032V/B/C		4064V/B/C			4128V/B/C			4256V/B/C				4384V/B/C		4512V/B/C	
Number of I/Os	30 ¹	32	30 ²	32	64	64	92 ³	96	64	96 ⁴	128	160	128	192	128	208
Number of GLBs	2	2	4	4	4	8	8	8	16	16	16	16	16	16	16	16
Number of I/Os / GLB	16	16	8	8	16	8	12	12	4	8	8	10	8	8	8	Mixture of 8 & 4 ⁵
Reference ORP Table	16 I/Os / GLB		8 I/Os / GLB		16 I/Os / GLB	8 I/Os / GLB	12 I/Os / GLB		4 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB	10 I/Os / GLB	8 I/Os / GLB		8 I/Os / GLB	8 I/Os / GLB 4 I/Os / GLB

1. 32-macrocell device, 44 TQFP: 2 GLBs have 15 out of 16 I/Os bonded out.

2. 64-macrocells device, 44 TQFP: 2 GLBs have 7 out of 8 I/Os bonded out.

3. 128-macrocell device, 128 TQFP: 4 GLBs have 11 out of 12 I/Os

4. 256-macrocell device, 144 TQFP: 16 GLBs have 6 I/Os per

5. 512-macrocell device: 20 GLBs have 8 I/Os per, 12 GLBs have 4 I/Os per

ispMACH 4000Z ORP Reference Table

	4032Z	4064Z		4128Z		4256Z		
Number of I/Os	32	32	64	64	96	64	96 ¹	128
Number of GLBs	2	4	4	8	8	16	16	16
Number of I/Os / GLB	16	8	16	8	12	4	8	8
Reference ORP Table	16 I/Os / GLB	8 I/Os / GLB	16 I/Os / GLB	8 I/Os / GLB	12 I/Os / GLB	4 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB

1. 256-macrocell device, 132 csBGA: 16 GLBs have 6 I/Os per

ispMACH 4000V/B/C/Z Power Supply and NC Connections¹

Signal	44-pin TQFP ²	48-pin TQFP ²	56-ball csBGA ³	100-pin TQFP ²	128-pin TQFP ²
VCC	11, 33	12, 36	K2, A9	25, 40, 75, 90	32, 51, 96, 115
VCCO0 VCCO (Bank 0)	6	6	F3	13, 33, 95	3, 17, 30, 41, 122
VCCO1 VCCO (Bank 1)	28	30	E8	45, 63, 83	58, 67, 81, 94, 105
GND	12, 34	13, 37	H3, C8	1, 26, 51, 76	1, 33, 65, 97
GND (Bank 0)	5	5	D3	7, 18, 32, 96	10, 24, 40, 113, 123
GND (Bank 1)	27	29	G8	46, 57, 68, 82	49, 59, 74, 88, 104
NC	—	—	4032Z: A8, B10, E1, E3, F8, F10, J1, K3	—	—

1. All grounds must be electrically connected at the board level. However, for the purposes of I/O current loading, grounds are associated with the bank shown.
2. Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.
3. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.

**ispMACH 4032V/B/C and 4064V/B/C Logic Signal Connections:
44-Pin TQFP**

Pin Number	Bank Number	ispMACH 4032V/B/C		ispMACH 4064V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	TDI	-	TDI	-
2	0	A5	A ⁵	A10	A ⁵
3	0	A6	A ⁶	A12	A ⁶
4	0	A7	A ⁷	A14	A ⁷
5	0	GND (Bank 0)	-	GND (Bank 0)	-
6	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
7	0	A8	A ⁸	B0	B ⁰
8	0	A9	A ⁹	B2	B ¹
9	0	A10	A ¹⁰	B4	B ²
10	-	TCK	-	TCK	-
11	-	VCC	-	VCC	-
12	-	GND	-	GND	-
13	0	A12	A ¹²	B8	B ⁴
14	0	A13	A ¹³	B10	B ⁵
15	0	A14	A ¹⁴	B12	B ⁶
16	0	A15	A ¹⁵	B14	B ⁷
17	1	CLK2/I	-	CLK2/I	-
18	1	B0	B ⁰	C0	C ⁰
19	1	B1	B ¹	C2	C ¹
20	1	B2	B ²	C4	C ²
21	1	B3	B ³	C6	C ³
22	1	B4	B ⁴	C8	C ⁴
23	-	TMS	-	TMS	-
24	1	B5	B ⁵	C10	C ⁵
25	1	B6	B ⁶	C12	C ⁶
26	1	B7	B ⁷	C14	C ⁷
27	1	GND (Bank 1)	-	GND (Bank 1)	-
28	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
29	1	B8	B ⁸	D0	D ⁰
30	1	B9	B ⁹	D2	D ¹
31	1	B10	B ¹⁰	D4	D ²
32	-	TDO	-	TDO	-
33	-	VCC	-	VCC	-
34	-	GND	-	GND	-
35	1	B12	B ¹²	D8	D ⁴
36	1	B13	B ¹³	D10	D ⁵
37	1	B14	B ¹⁴	D12	D ⁶
38	1	B15/GOE1	B ¹⁵	D14/GOE1	D ⁷
39	0	CLK0/I	-	CLK0/I	-
40	0	A0/GOE0	A ⁰	A0/GOE0	A ⁰
41	0	A1	A ¹	A2	A ¹

ispMACH 4032Z and 4064Z Logic Signal Connections: 56-Ball csBGA (Cont.)

Ball Number	Bank Number	ispMACH 4032Z		ispMACH 4064Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
K5	0	A15	A ¹⁵	B0	B ⁰
H6	0	CLK1/I	-	CLK1/I	-
K6	1	CLK2/I	-	CLK2/I	-
H7	1	B0	B ⁰	C0	C ⁰
K7	1	B1	B ¹	C1	C ¹
K8	1	B2	B ²	C2	C ²
K9	1	B3	B ³	C4	C ³
K10	1	B4	B ⁴	C6	C ⁴
J10	-	TMS	-	TMS	-
H8	1	B5	B ⁵	C8	C ⁵
H10	1	B6	B ⁶	C10	C ⁶
G10	1	B7	B ⁷	C11	C ⁷
G8	1	GND (Bank 1)	-	GND (Bank 1)	-
F8	1	NC ¹	-	I ¹	-
F10	1	NC ¹	-	I ¹	-
E8	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
E10	1	B8	B ⁸	D15	D ⁷
D8	1	B9	B ⁹	D12	D ⁶
D10	1	B10	B ¹⁰	D10	D ⁵
C10	1	B11	B ¹¹	D8	D ⁴
B10	1	NC ¹	-	I ¹	-
A10	-	TDO	-	TDO	-
A9	-	VCC	-	VCC	-
C8	-	GND	-	GND	-
A8	1	NC ¹	-	I ¹	-
A7	1	B12	B ¹²	D6	D ³
C7	1	B13	B ¹³	D4	D ²
C6	1	B14	B ¹⁴	D2	D ¹
A6	1	B15/GOE1	B ¹⁵	D0/GOE1	D ⁰
C5	1	CLK3/I	-	CLK3/I	-
A5	0	CLK0/I	-	CLK0/I	-
C4	0	A0/GOE0	A ⁰	A0/GOE0	A ⁰
A4	0	A1	A ¹	A1	A ¹
A3	0	A2	A ²	A2	A ²
A2	0	A3	A ³	A4	A ³
A1	0	A4	A ⁴	A6	A ⁴

1. For device migration considerations, these NC pins are input signal pins in ispMACH 4064Z devices.

ispMACH 4128V/B/C Logic Signal Connections: 128-Pin TQFP (Cont.)

Pin Number	Bank Number	ispMACH 4128V/B/C	
		GLB/MC/Pad	ORP
62	1	E10	E^8
63	1	E12	E^9
64	1	E14	E^11
65	1	GND	-
66	1	TMS	-
67	1	VCCO (Bank 1)	-
68	1	F0	F^0
69	1	F1	F^1
70	1	F2	F^2
71	1	F4	F^3
72	1	F5	F^4
73	1	F6	F^5
74	1	GND (Bank 1)	-
75	1	F8	F^6
76	1	F9	F^7
77	1	F10	F^8
78	1	F12	F^9
79	1	F13	F^10
80	1	F14	F^11
81	1	VCCO (Bank 1)	-
82	1	G14	G^11
83	1	G13	G^10
84	1	G12	G^9
85	1	G10	G^8
86	1	G9	G^7
87	1	G8	G^6
88	1	GND (Bank 1)	-
89	1	G6	G^5
90	1	G5	G^4
91	1	G4	G^3
92	1	G2	G^2
93	1	G0	G^0
94	1	VCCO (Bank 1)	-
95	1	TDO	-
96	1	VCC	-
97	1	GND	-
98	1	H14	H^11
99	1	H13	H^10
100	1	H12	H^9
101	1	H10	H^8
102	1	H9	H^7
103	1	H8	H^6
104	1	GND (Bank 1)	-

**ispMACH 4064Z, 4128Z and 4256Z Logic Signal Connections:
132-Ball csBGA (Cont.)**

Ball Number	Bank Number	ispMACH 4064Z		ispMACH 4128Z		ispMACH 4256Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
E3	0	NC	-	B8	B ⁶	D12	D ⁶
F2	0	A12	A ¹²	B9	B ⁷	D10	D ⁵
F1	0	A13	A ¹³	B10	B ⁸	D8	D ⁴
F3	0	A14	A ¹⁴	B12	B ⁹	D6	D ³
G1	0	A15	A ¹⁵	B13	B ¹⁰	D4	D ²
G2	0	I	-	B14	B ¹¹	D2	D ¹
G3	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
H2	0	NC	-	C14	C ¹¹	E2	E ¹
H1	0	B15	B ¹⁵	C13	C ¹⁰	E4	E ²
H3	0	B14	B ¹⁴	C12	C ⁹	E6	E ³
J1	0	B13	B ¹³	C10	C ⁸	E8	E ⁴
J2	0	B12	B ¹²	C9	C ⁷	E10	E ⁵
J3	0	NC	-	C8	C ⁶	E12	E ⁶
K2	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
K1	0	NC	-	C6	C ⁵	F2	F ¹
K3	0	B11	B ¹¹	C5	C ⁴	F4	F ²
L2	0	B10	B ¹⁰	C4	C ³	F6	F ³
L1	0	B9	B ⁹	C2	C ²	F8	F ⁴
L3	0	B8	B ⁸	C1	C ¹	F10	F ⁵
M1	0	I	-	C0	C ⁰	F12	F ⁶
M2	0	NC	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
N1	-	TCK	-	TCK	-	TCK	-
P1	-	VCC	-	VCC	-	VCC	-
P2	-	GND	-	GND	-	GND	-
N2	0	I	-	D14	D ¹¹	G12	G ⁶
P3	0	B7	B ⁷	D13	D ¹⁰	G10	G ⁵
M3	0	B6	B ⁶	D12	D ⁹	G8	G ⁴
N3	0	B5	B ⁵	D10	D ⁸	G6	G ³
P4	0	B4	B ⁴	D9	D ⁷	G4	G ²
M4	0	NC	-	D8	D ⁶	G2	G ¹
N4	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
P5	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
N5	0	NC	-	D6	D ⁵	H12	H ⁶
M5	0	B3	B ³	D5	D ⁴	H10	H ⁵
N6	0	B2	B ²	D4	D ³	H8	H ⁴
P6	0	B1	B ¹	D2	D ²	H6	H ³
M6	0	B0	B ⁰	D1	D ¹	H4	H ²
P7	0	NC	-	D0	D ⁰	H2	H ¹
N7	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
M7	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
N8	-	VCC	-	VCC	-	VCC	-

**ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections:
176-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
19	0	D4	D [^] 2	E4	E [^] 2	G4	G [^] 2
20	0	D2	D [^] 1	E2	E [^] 1	G2	G [^] 1
21	0	D0	D [^] 0	E0	E [^] 0	G0	G [^] 0
22	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
23	0	E0	E [^] 0	H0	H [^] 0	J0	J [^] 0
24	0	E2	E [^] 1	H2	H [^] 1	J2	J [^] 1
25	0	E4	E [^] 2	H4	H [^] 2	J4	J [^] 2
26	0	E6	E [^] 3	H6	H [^] 3	J6	J [^] 3
27	0	E8	E [^] 4	H8	H [^] 4	J8	J [^] 4
28	0	E10	E [^] 5	H10	H [^] 5	J10	J [^] 5
29	0	E12	E [^] 6	H12	H [^] 6	J12	J [^] 6
30	0	E14	E [^] 7	H14	H [^] 7	J14	J [^] 7
31	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
32	0	F0	F [^] 0	J0	J [^] 0	N0	N [^] 0
33	0	F2	F [^] 1	J2	J [^] 1	N2	N [^] 1
34	0	F4	F [^] 2	J4	J [^] 2	N4	N [^] 2
35	0	F6	F [^] 3	J6	J [^] 3	N6	N [^] 3
36	0	F8	F [^] 4	J8	J [^] 4	N8	N [^] 4
37	0	F10	F [^] 5	J10	J [^] 5	N10	N [^] 5
38	0	F12	F [^] 6	J12	J [^] 6	N12	N [^] 6
39	0	F14	F [^] 7	J14	J [^] 7	N14	N [^] 7
40	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
41	-	TCK	-	TCK	-	TCK	-
42	-	VCC	-	VCC	-	VCC	-
43	-	NC	-	NC	-	NC	-
44	-	NC	-	NC	-	NC	-
45	-	NC	-	NC	-	NC	-
46	-	GND	-	GND (Bank 0)	-	GND	-
47	0	G14	G [^] 7	K14	K [^] 7	O14	O [^] 7
48	0	G12	G [^] 6	K12	K [^] 6	O12	O [^] 6
49	0	G10	G [^] 5	K10	K [^] 5	O10	O [^] 5
50	0	G8	G [^] 4	K8	K [^] 4	O8	O [^] 4
51	0	G6	G [^] 3	K6	K [^] 3	O6	O [^] 3
52	0	G4	G [^] 2	K4	K [^] 2	O4	O [^] 2
53	0	G2	G [^] 1	K2	K [^] 1	O2	O [^] 1
54	0	G0	G [^] 0	K0	K [^] 0	O0	O [^] 0
55	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
56	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
57	0	H14	H [^] 7	L14	L [^] 7	P14	P [^] 7
58	0	H12	H [^] 6	L12	L [^] 6	P12	P [^] 6
59	0	H10	H [^] 5	L10	L [^] 5	P10	P [^] 5

**ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections:
176-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
142	1	O0	O ⁰	GX0	GX ⁰	OX0	OX ⁰
143	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
144	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
145	1	P14	P ⁷	HX14	HX ⁷	PX14	PX ⁷
146	1	P12	P ⁶	HX12	HX ⁶	PX12	PX ⁶
147	1	P10	P ⁵	HX10	HX ⁵	PX10	PX ⁵
148	1	P8	P ⁴	HX8	HX ⁴	PX8	PX ⁴
149	1	P6	P ³	HX6	HX ³	PX6	PX ³
150	1	P4	P ²	HX4	HX ²	PX4	PX ²
151	1	P2/GOE1	P ¹	HX2/GOE1	HX ¹	PX2/GOE1	PX ¹
152	1	P0	P ⁰	HX0	HX ⁰	PX0	PX ⁰
153	-	GND	-	GND	-	GND	-
154	1	CLK3/I	-	CLK3/I	-	CLK3/I	-
155	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
156	0	CLK0/I	-	CLK0/I	-	CLK0/I	-
157	-	VCC	-	VCC	-	VCC	-
158	0	A0	A ⁰	A0	A ⁰	A0	A ⁰
159	0	A2/GOE0	A ¹	A2/GOE0	A ¹	A2/GOE0	A ¹
160	0	A4	A ²	A4	A ²	A4	A ²
161	0	A6	A ³	A6	A ³	A6	A ³
162	0	A8	A ⁴	A8	A ⁴	A8	A ⁴
163	0	A10	A ⁵	A10	A ⁵	A10	A ⁵
164	0	A12	A ⁶	A12	A ⁶	A12	A ⁶
165	0	A14	A ⁷	A14	A ⁷	A14	A ⁷
166	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
167	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
168	0	B0	B ⁰	B0	B ⁰	B0	B ⁰
169	0	B2	B ¹	B2	B ¹	B2	B ¹
170	0	B4	B ²	B4	B ²	B4	B ²
171	0	B6	B ³	B6	B ³	B6	B ³
172	0	B8	B ⁴	B8	B ⁴	B8	B ⁴
173	0	B10	B ⁵	B10	B ⁵	B10	B ⁵
174	0	B12	B ⁶	B12	B ⁶	B12	B ⁶
175	0	B14	B ⁷	B14	B ⁷	B14	B ⁷
176	-	VCC	-	VCC	-	VCC	-

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:
256-Ball ftBGA/fpBGA (Cont.)**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
R14	1	J10	J ⁵	J10	J ⁷	N10	N ⁵	BX10	BX ⁵
P13	1	J12	J ⁶	J12	J ⁸	N12	N ⁶	BX12	BX ⁶
N13	1	J14	J ⁷	J14	J ⁹	N14	N ⁷	BX14	BX ⁷
M12	1	NC	-	NC	-	P4	P ²	FX0	FX ⁰
T15	1	NC	-	NC	-	P6	P ³	FX2	FX ¹
-	-	VCC	-	VCC	-	VCC	-	VCC	-
-	-	GND	-	GND	-	GND	-	GND	-
-	1	-	-	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
P14	-	TMS	-	TMS	-	TMS	-	TMS	-
-	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
L12	1	NC	-	NC	-	NC	-	FX4	FX ²
R16	1	NC	-	NC	-	P8	P ⁴	FX6	FX ³
N14	1	NC	-	NC	-	P10	P ⁵	FX8	FX ⁴
P15	1	K14	K ⁷	K14	K ⁹	O14	O ⁷	CX14	CX ⁷
L11	1	K12	K ⁶	K12	K ⁸	O12	O ⁶	CX12	CX ⁶
P16	1	K10	K ⁵	K10	K ⁷	O10	O ⁵	CX10	CX ⁵
K11	1	K8	K ⁴	K9	K ⁶	O8	O ⁴	CX8	CX ⁴
M14	1	K6	K ³	K8	K ⁵	O6	O ³	CX6	CX ³
K12	1	K4	K ²	K6	K ⁴	O4	O ²	CX4	CX ²
N15	1	K2	K ¹	K4	K ³	O2	O ¹	CX2	CX ¹
N16	1	K0	K ⁰	K2	K ²	O0	O ⁰	CX0	CX ⁰
M15	1	NC	-	K1	K ¹	BX6	BX ³	HX0	HX ⁰
M13	1	NC	-	K0	K ⁰	BX4	BX ²	HX4	HX ¹
-	1	-	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
-	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
M16	1	NC	-	NC	-	NC	-	FX10	FX ⁵
L15	1	NC	-	NC	-	P12	P ⁶	FX12	FX ⁶
L16	1	NC	-	NC	-	P14	P ⁷	FX14	FX ⁷
J11	1	NC	-	L14	L ⁹	BX2	BX ¹	HX8	HX ²
K15	1	NC	-	L12	L ⁸	BX0	BX ⁰	HX12	HX ³
J12	1	L14	L ⁷	L10	L ⁷	AX14	AX ⁷	GX14	GX ⁷
K13	1	L12	L ⁶	L9	L ⁶	AX12	AX ⁶	GX12	GX ⁶
K14	1	L10	L ⁵	L8	L ⁵	AX10	AX ⁵	GX10	GX ⁵
K16	1	L8	L ⁴	L6	L ⁴	AX8	AX ⁴	GX8	GX ⁴
J16	1	L6	L ³	L4	L ³	AX6	AX ³	GX6	GX ³
J15	1	L4	L ²	L2	L ²	AX4	AX ²	GX4	GX ²
H16	1	L2	L ¹	L1	L ¹	AX2	AX ¹	GX2	GX ¹
J13	1	L0	L ⁰	L0	L ⁰	AX0	AX ⁰	GX0	GX ⁰
-	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
-	1	-	-	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
J14	1	M0	M ⁰	M0	M ⁰	DX0	DX ⁰	JX0	JX ⁰

ispMACH 4000B (2.5V) Industrial Devices (Cont.)

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4384B	LC4384B-5FT256I	384	2.5	5	ftBGA	256	192	I
	LC4384B-75FT256I	384	2.5	7.5	ftBGA	256	192	I
	LC4384B-10FT256I	384	2.5	10	ftBGA	256	192	I
	LC4384B-5F256I ¹	384	2.5	5	fpBGA	256	192	I
	LC4384B-75F256I ¹	384	2.5	7.5	fpBGA	256	192	I
	LC4384B-10F256I ¹	384	2.5	10	fpBGA	256	192	I
	LC4384B-5T176I	384	2.5	5	TQFP	176	128	I
	LC4384B-75T176I	384	2.5	7.5	TQFP	176	128	I
	LC4384B-10T176I	384	2.5	10	TQFP	176	128	I
LC4512B	LC4512B-5FT256I	512	2.5	5	ftBGA	256	208	I
	LC4512B-75FT256I	512	2.5	7.5	ftBGA	256	208	I
	LC4512B-10FT256I	512	2.5	10	ftBGA	256	208	I
	LC4512B-5F256I ¹	512	2.5	5	fpBGA	256	208	I
	LC4512B-75F256I ¹	512	2.5	7.5	fpBGA	256	208	I
	LC4512B-10F256I ¹	512	2.5	10	fpBGA	256	208	I
	LC4512B-5T176I	512	2.5	5	TQFP	176	128	I
	LC4512B-75T176I	512	2.5	7.5	TQFP	176	128	I
	LC4512B-10T176I	512	2.5	10	TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000V (3.3V) Commercial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-25T48C	32	3.3	2.5	TQFP	48	32	C
	LC4032V-5T48C	32	3.3	5	TQFP	48	32	C
	LC4032V-75T48C	32	3.3	7.5	TQFP	48	32	C
	LC4032V-25T44C	32	3.3	2.5	TQFP	44	30	C
	LC4032V-5T44C	32	3.3	5	TQFP	44	30	C
	LC4032V-75T44C	32	3.3	7.5	TQFP	44	30	C
LC4064V	LC4064V-25T100C	64	3.3	2.5	TQFP	100	64	C
	LC4064V-5T100C	64	3.3	5	TQFP	100	64	C
	LC4064V-75T100C	64	3.3	7.5	TQFP	100	64	C
	LC4064V-25T48C	64	3.3	2.5	TQFP	48	32	C
	LC4064V-5T48C	64	3.3	5	TQFP	48	32	C
	LC4064V-75T48C	64	3.3	7.5	TQFP	48	32	C
	LC4064V-25T44C	64	3.3	2.5	TQFP	44	30	C
	LC4064V-5T44C	64	3.3	5	TQFP	44	30	C
	LC4064V-75T44C	64	3.3	7.5	TQFP	44	30	C

ispMACH 4000V (3.3V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4512V	LC4512V-35FT256C	512	3.3	3.5	ftBGA	256	208	C
	LC4512V-5FT256C	512	3.3	5	ftBGA	256	208	C
	LC4512V-75FT256C	512	3.3	7.5	ftBGA	256	208	C
	LC4512V-35F256C ¹	512	3.3	3.5	fpBGA	256	208	C
	LC4512V-5F256C ¹	512	3.3	5	fpBGA	256	208	C
	LC4512V-75F256C ¹	512	3.3	7.5	fpBGA	256	208	C
	LC4512V-35T176C	512	3.3	3.5	TQFP	176	128	C
	LC4512V-5T176C	512	3.3	5	TQFP	176	128	C
	LC4512V-75T176C	512	3.3	7.5	TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000V (3.3V) Industrial Devices

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-5T48I	32	3.3	5	TQFP	48	32	I
	LC4032V-75T48I	32	3.3	7.5	TQFP	48	32	I
	LC4032V-10T48I	32	3.3	10	TQFP	48	32	I
	LC4032V-5T44I	32	3.3	5	TQFP	44	30	I
	LC4032V-75T44I	32	3.3	7.5	TQFP	44	30	I
	LC4032V-10T44I	32	3.3	10	TQFP	44	30	I
LC4064V	LC4064V-5T100I	64	3.3	5	TQFP	100	64	I
	LC4064V-75T100I	64	3.3	7.5	TQFP	100	64	I
	LC4064V-10T100I	64	3.3	10	TQFP	100	64	I
	LC4064V-5T48I	64	3.3	5	TQFP	48	32	I
	LC4064V-75T48I	64	3.3	7.5	TQFP	48	32	I
	LC4064V-10T48I	64	3.3	10	TQFP	48	32	I
	LC4064V-5T44I	64	3.3	5	TQFP	44	30	I
	LC4064V-75T44I	64	3.3	7.5	TQFP	44	30	I
	LC4064V-10T44I	64	3.3	10	TQFP	44	30	I
LC4128V	LC4128V-5T144I	128	3.3	5	TQFP	144	96	I
	LC4128V-75T144I	128	3.3	7.5	TQFP	144	96	I
	LC4128V-10T144I	128	3.3	10	TQFP	144	96	I
	LC4128V-5T128I	128	3.3	5	TQFP	128	92	I
	LC4128V-75T128I	128	3.3	7.5	TQFP	128	92	I
	LC4128V-10T128I	128	3.3	10	TQFP	128	92	I
	LC4128V-5T100I	128	3.3	5	TQFP	100	64	I
	LC4128V-75T100I	128	3.3	7.5	TQFP	100	64	I
	LC4128V-10T100I	128	3.3	10	TQFP	100	64	I

ispMACH 4000C (1.8V) Lead-Free Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4256C	LC4256C-5FTN256AI	256	1.8	5	Lead-free ftBGA	256	128	I
	LC4256C-75FTN256AI	256	1.8	7.5	Lead-free ftBGA	256	128	I
	LC4256C-10FTN256AI	256	1.8	10	Lead-free ftBGA	256	128	I
	LC4256C-5FTN256BI	256	1.8	5	Lead-free ftBGA	256	160	I
	LC4256C-75FTN256BI	256	1.8	7.5	Lead-free ftBGA	256	160	I
	LC4256C-10FTN256BI	256	1.8	10	Lead-free ftBGA	256	160	I
	LC4256C-5FN256AI ¹	256	1.8	5	Lead-free fpBGA	256	128	I
	LC4256C-75FN256AI ¹	256	1.8	7.5	Lead-free fpBGA	256	128	I
	LC4256C-10FN256AI ¹	256	1.8	10	Lead-free fpBGA	256	128	I
	LC4256C-5FN256BI ¹	256	1.8	5	Lead-free fpBGA	256	160	I
	LC4256C-75FN256BI ¹	256	1.8	7.5	Lead-free fpBGA	256	160	I
	LC4256C-10FN256BI ¹	256	1.8	10	Lead-free fpBGA	256	160	I
	LC4256C-5TN176I	256	1.8	5	Lead-free TQFP	176	128	I
	LC4256C-75TN176I	256	1.8	7.5	Lead-free TQFP	176	128	I
	LC4256C-10TN176I	256	1.8	10	Lead-free TQFP	176	128	I
	LC4256C-5TN100I	256	1.8	5	Lead-free TQFP	100	64	I
	LC4256C-75TN100I	256	1.8	7.5	Lead-free TQFP	100	64	I
	LC4256C-10TN100I	256	1.8	10	Lead-free TQFP	100	64	I
LC4384C	LC4384C-5FTN256I	384	1.8	5	Lead-free ftBGA	256	192	I
	LC4384C-75FTN256I	384	1.8	7.5	Lead-free ftBGA	256	192	I
	LC4384C-10FTN256I	384	1.8	10	Lead-free ftBGA	256	192	I
	LC4384C-5FN256I ¹	384	1.8	5	Lead-free fpBGA	256	192	I
	LC4384C-75FN256I ¹	384	1.8	7.5	Lead-free fpBGA	256	192	I
	LC4384C-10FN256I ¹	384	1.8	10	Lead-free fpBGA	256	192	I
	LC4384C-5TN176I	384	1.8	5	Lead-free TQFP	176	128	I
	LC4384C-75TN176I	384	1.8	7.5	Lead-free TQFP	176	128	I
	LC4384C-10TN176I	384	1.8	10	Lead-free TQFP	176	128	I
LC4512C	LC4512C-5FTN256I	512	1.8	5	Lead-free ftBGA	256	208	I
	LC4512C-75FTN256I	512	1.8	7.5	Lead-free ftBGA	256	208	I
	LC4512C-10FTN256I	512	1.8	10	Lead-free ftBGA	256	208	I
	LC4512C-5FN256I ¹	512	1.8	5	Lead-free fpBGA	256	208	I
	LC4512C-75FN256I ¹	512	1.8	7.5	Lead-free fpBGA	256	208	I
	LC4512C-10FN256I ¹	512	1.8	10	Lead-free fpBGA	256	208	I
	LC4512C-5TN176I	512	1.8	5	Lead-free TQFP	176	128	I
	LC4512C-75TN176I	512	1.8	7.5	Lead-free TQFP	176	128	I
	LC4512C-10TN176I	512	1.8	10	Lead-free TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.